

Tokyo Electron Ltd. Alpha303i-K Configuration

Type: Vertical LPCVD Furnace

Serial Number:

Currently Configured for 300mm wafer size

MFG Date: 2004 Process Type: TEOS

EQUIPMENT DETAILS:

Tool status: Warehouse.

1.Base Unit for TEOS Process

Including:

Cabinets / Horiba MFC / Controllers Included

- Furnace Cabinet' (Including Clean Air Flow System)
- Scavenger and Water Cooling Unit
- Power Supply Unit (U/P Box) (Including Control Unit, Transformers, SCR, and Breaker Unit)
- Main Controller (WAVES)
- Temperature Controller M560
- 2. FOUP and Wafer Handling Automation Included
- FOUP Load Port
- FOUP Transfer
- 16 FOUP Stocker
- FIMS Port
- KHI Wafer Load Automation
- Variable Pitch Change Mechanism (w/5 fork)
- Auto Tube Shutter
- Boat Elevator w/Boat Rotation Mechanism
- 3. 100 wfs Normal Heater: VMM-56-002 Included
- excludes Outer/Inner T/C
- 4. Integrated Gas System in Gas Cabinet and TEOS LSC baking system
- O2 gas line (1 stick Included)
- TEOS gas line (1 stick Included)

- Purge N2
- Vacuum Vent
- Exhaust Vent
- Piping Tape Heater
- 5. Vacuum Configuration 1 Included
- 100A Vac. piping
- CKD Hot type Main Valve
- Vacuum Gage & pressure switch
- 6. Per System Options
- (a) N2 Load Lock excluded
- (b) Single Boat Operation
- (c) N2 boat cooling shower exclude
- (d) 2 FOUP Load port
- (e) B.S sensor 0-10 Torr, 0-1000 Torr
- (f) AC Power BOX Voltage : 208 V ,3Phase, 4Wire
- 7. Missing Parts :

Manifold & Cold Trap